

SOLDER PASTE

# BGA LEAD SOLDER PASTE



Sn63/Pb37

Melting point 183°C



---

# Product Usage



## TIN PASTE

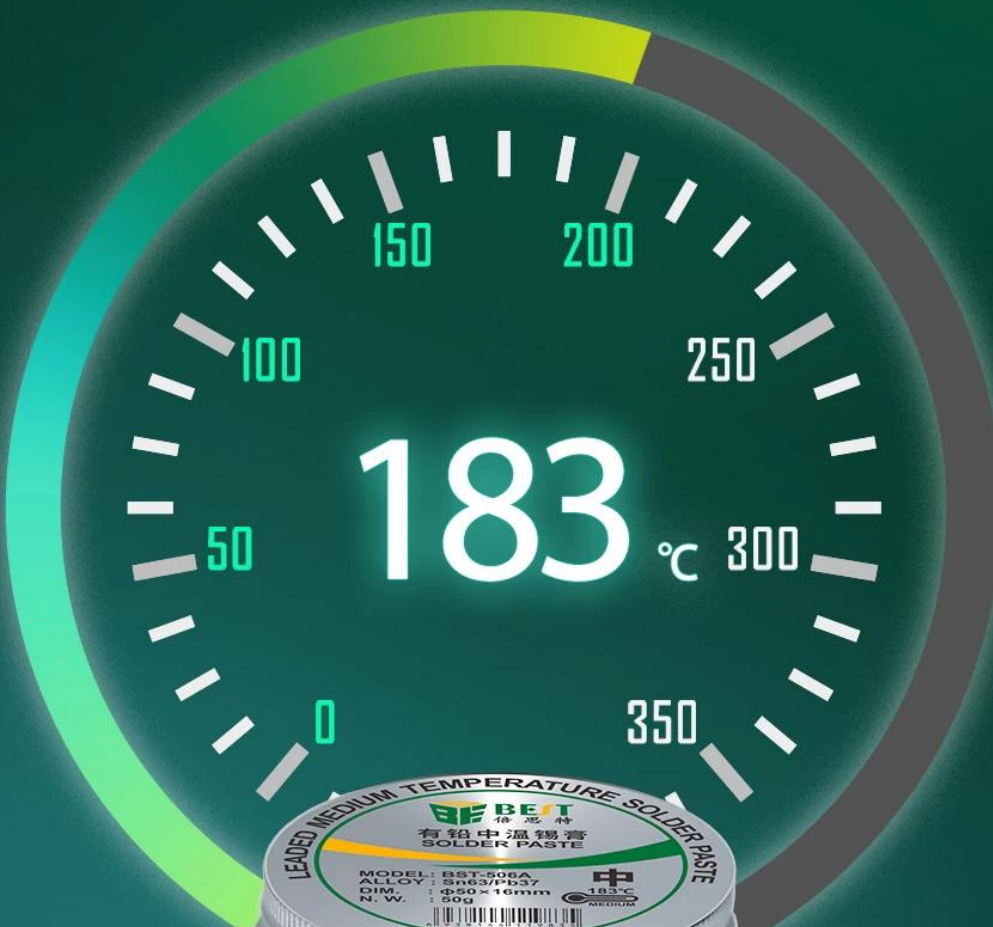
<b>Model</b>	BST-506A
<b>Name</b>	Moderate temperature Solder paste
<b>Composition</b>	Sn63/Pb37
<b>Melting point</b>	183°C
<b>G.W.</b>	50g
<b>Granule</b>	20~38μm
<b>Size</b>	φ50*16mm

---

Sn63/Pb37

Lead-containing mid-temperature melting point

183°C





Low residue

Fine grain

Rapid welding

Solder spot bright





# Welding requirements for a wide range of products



**SMT  
patch**



**LED  
patch**



**BGA  
welding**

# Product Size



G.W.:50g

